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March 2015

FDD6688/FDU6688

30V N-Channel PowerTrench® MOSFET

General Description

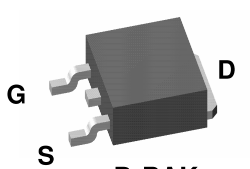
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{DS(ON)}$ and fast switching speed.

Applications

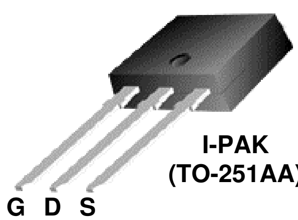
- DC/DC converter
- Motor Drives

Features

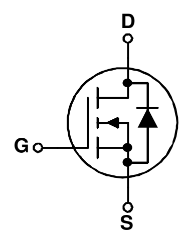
- 84 A, 30 V. $R_{DS(ON)} = 5\ m\Omega$ @ $V_{GS} = 10\ V$
  $R_{DS(ON)} = 6\ m\Omega$ @ $V_{GS} = 4.5\ V$
- Low gate charge
- Fast switching
- High performance trench technology for extremely low $R_{DS(ON)}$



D-PAK
(TO-252)



I-PAK
(TO-251AA)



Absolute Maximum Ratings

$T_A=25^oC$ unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±20	
I_D	Drain Current – Continuous	(Note 3)	84	A
	– Pulsed	(Note 1a)	100	
P_D	Power Dissipation for Single Operation	(Note 1)	83	W
		(Note 1a)	3.8	
		(Note 1b)	1.6	
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +175	°C

Thermal Characteristics

Symbol	Parameter		Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	40	
		(Note 1b)	96	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD6688	FDD6688	D-PAK (TO-252)	13''	16mm	2500 units
FDU6688	FDU6688	I-PAK (TO-251)	Tube	N/A	75

Electrical Characteristics

$T_A = 25°C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain-Source Avalanche Ratings (Note 2)						
W_{DSS}	Drain-Source Avalanche Energy	Single Pulse, V_{DD} = 15 V, I_D = 21A			370	mJ
I_{AR}	Drain-Source Avalanche Current				21	A
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 μA	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		24		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 24 V, V_{GS} = 0 V			1	μA
I_{GSS}	Gate–Body Leakage	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, I_D = 250 μA	1	1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		–5		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = 10 V, I_D = 18 A V_{GS} = 4.5 V, I_D = 16.5 A V_{GS} = 10 V, I_D = 18 A, T_J=125°C		4 5 6	5 6 10	mΩ
$I_{D(on)}$	On–State Drain Current	V_{GS} = 10 V, V_{DS} = 5 V	50			A
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 18 A		88		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 15 V, V_{GS} = 0 V, f = 1.0 MHz		3845		pF
C_{oss}	Output Capacitance			930		pF
C_{rss}	Reverse Transfer Capacitance			368		pF
R_G	Gate Resistance	V_{GS} = 15 mV, f = 1.0 MHz		1.2		Ω
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	V_{DD} = 15 V, I_D = 1 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		15	27	ns
t_r	Turn–On Rise Time			13	23	ns
$t_{d(off)}$	Turn–Off Delay Time			62	99	ns
t_f	Turn–Off Fall Time			36	58	ns
Q_g	Total Gate Charge	V_{DS} = 15V, I_D = 18 A, V_{GS} = 5 V		37	56	nC
Q_{gs}	Gate–Source Charge			10		nC
Q_{gd}	Gate–Drain Charge			14		nC

Electrical Characteristics (continued)

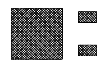
$T_A = 25°C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain–Source Diode Characteristics and Maximum Ratings						
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0$ V, $I_S = 3.2$ A (Note 2)		0.7	1.2	V
t_{rr}	Diode Reverse Recovery Time	$I_F = 18$ A, $d_{iF}/d_t = 100$ A/µs		39		nS
Q_{rr}	Diode Reverse Recovery Charge			31		nC

Notes:8

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) $R_{\theta JA} = 40°C/W$ when mounted on a $1in^2$ pad of 2 oz copper



b) $R_{\theta JA} = 96°C/W$ when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

3. Maximum current is calculated as: $\sqrt{\dfrac{P_D}{R_{DS(ON)}}}$

where P_D is maximum power dissipation at $T_C = 25°C$ and $R_{DS(on)}$ is at $T_{J(max)}$ and $V_{GS} = 10V$. Package current limitation is 21A

Typical Characteristics

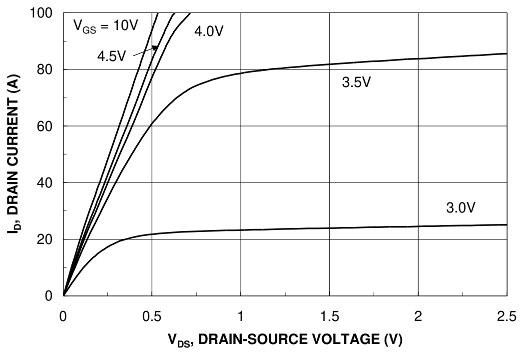


Figure 1. On-Region Characteristics.

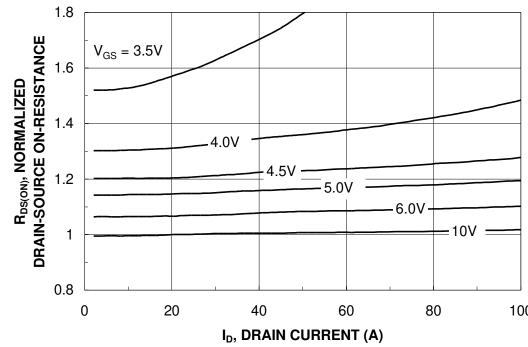


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

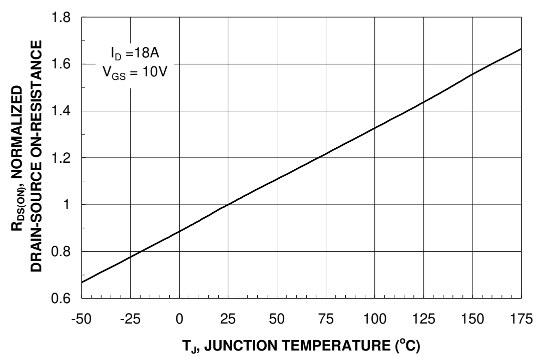


Figure 3. On-Resistance Variation with Temperature.

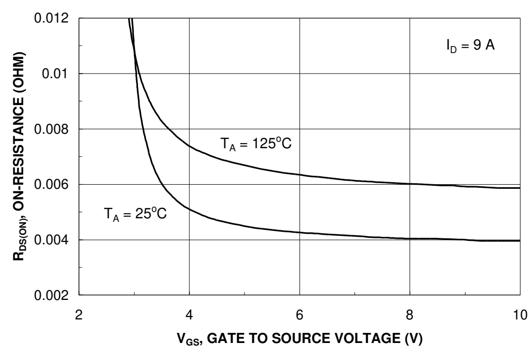


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

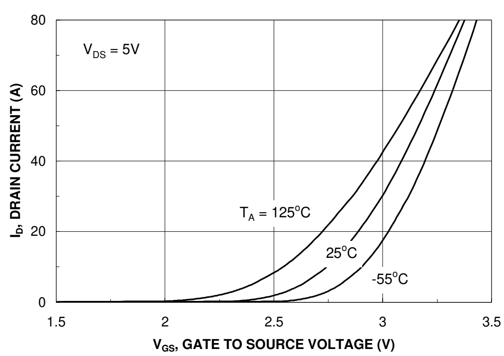


Figure 5. Transfer Characteristics

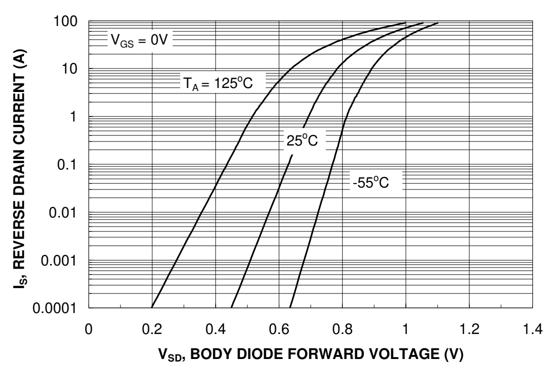


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics

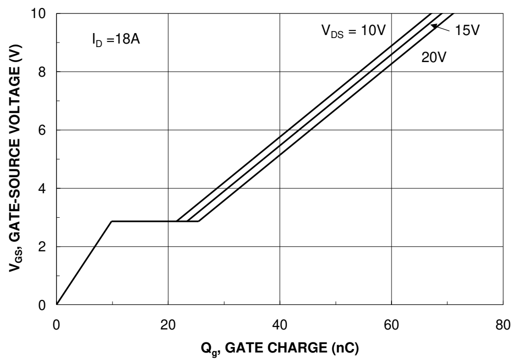


Figure 7. Gate Charge Characteristics

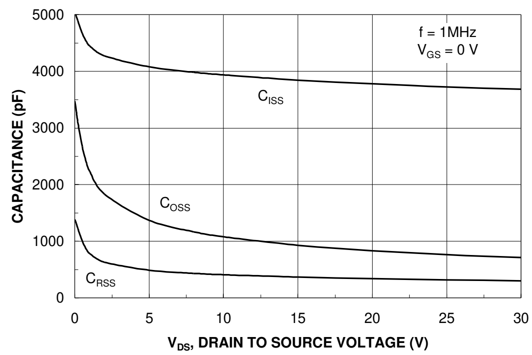


Figure 8. Capacitance Characteristics

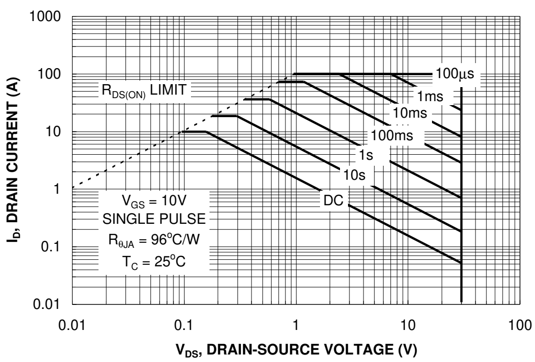


Figure 9. Maximum Safe Operating Area

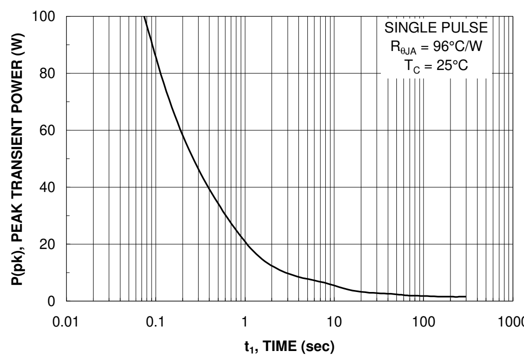


Figure 10. Single Pulse Maximum Power Dissipation

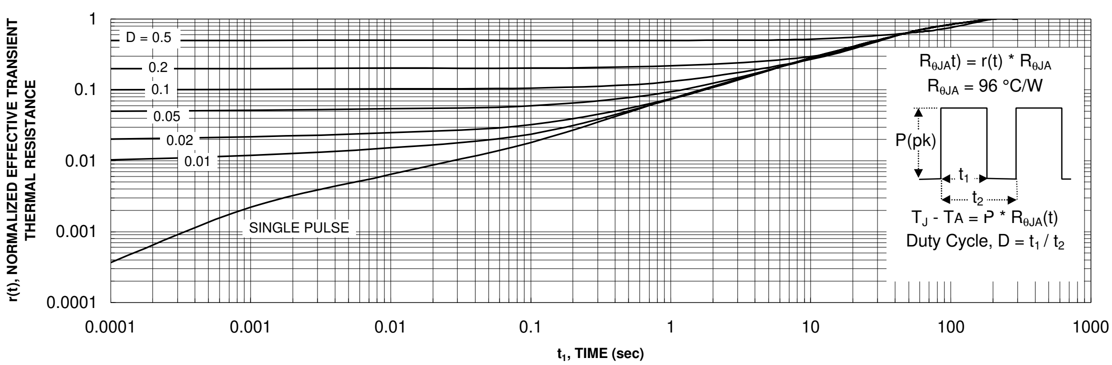
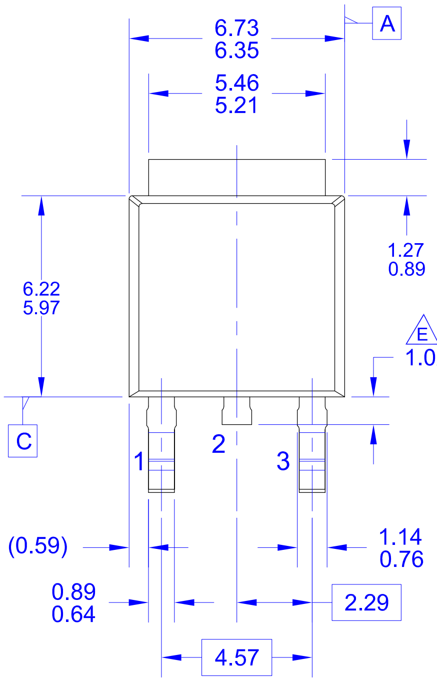
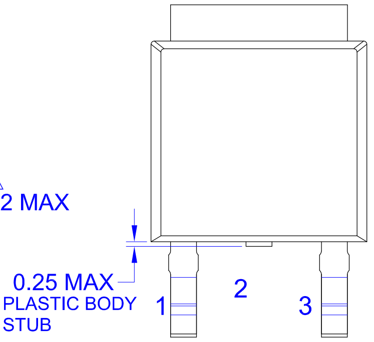


Figure 11. Transient Thermal Response Curve

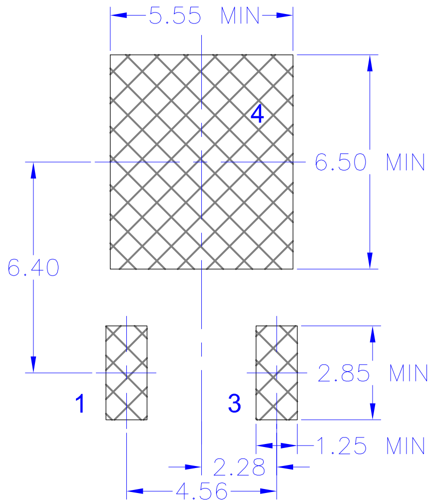
Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.



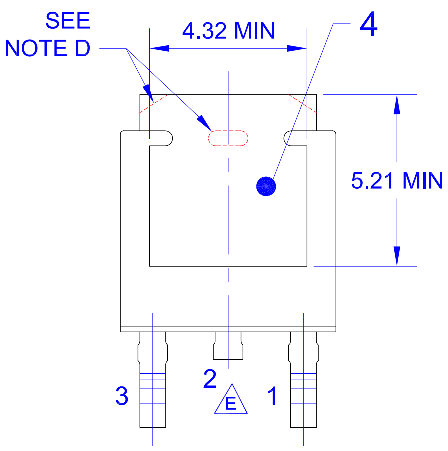
NON-DIODE PRODUCTS VERSION



DIODE PRODUCTS VERSION



LAND PATTERN RECOMMENDATION



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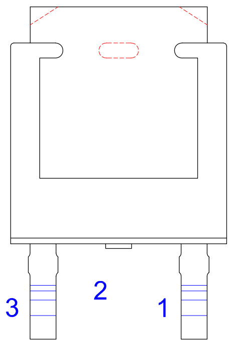

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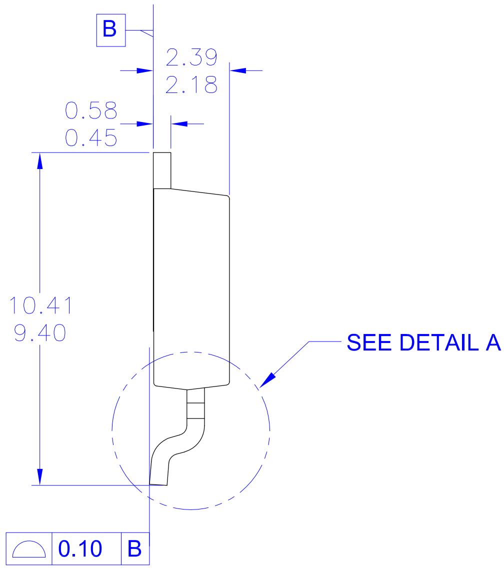

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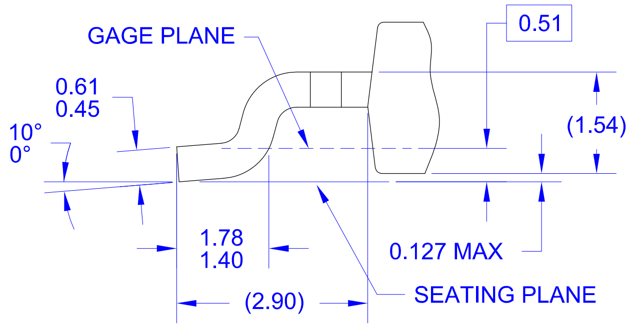
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) TRIMMED CENTER LEAD IS PRESENT ONLY FOR DIODE PRODUCTS
- F) DIMENSIONS ARE EXCLUSSIVE OF BURSS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD TO228P991X239-3N.
- H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV10



DETAIL A
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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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